

# Multilayer FPC for High-Speed Transmission

## Multilayer FPC having a function similar to a rigid flexible printed board!

Can be suited to use of a high frequency of several tens of GHz by reducing a reflection point without the connecting point between FPC and PCB.

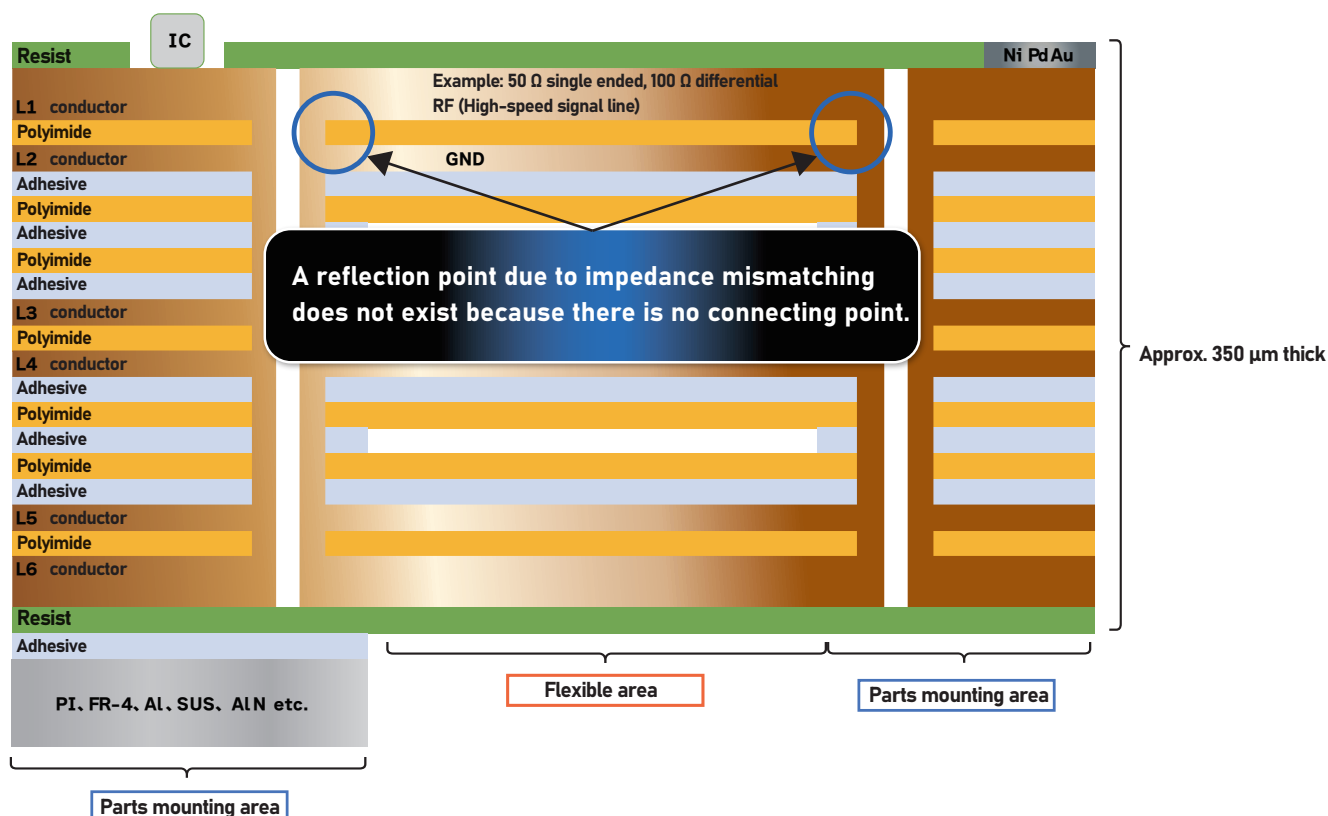


Number of layers	: 3 to 8
Connecting via	: Through-via, blind via, and filled via
Base materials	: Polyimide and liquid crystal polymer
FPC thickness	: FPC thickness: Approx. 200 to 800 $\mu\text{m}$
Surface treatment	: Gold flash plating, nickel palladium gold plating, and lead-free solder plating

## Features

- Measures for heat radiation can be taken by attaching a reinforcing such as a metal or ceramics.
- Can be miniaturized using a high-density RF line.
- Can be used for wire bonding.

## Example of layer structure



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